12th Annual International Wafer-Level Packaging Conference (IWLPC 2015)

Interconnecting WLP, MEMS & 2.5/3D Integration

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Sessions at a Glance: Tuesday, October 13

7:00 AM	**Registration Opens** **Bayshore Foyer**		
	WLP TRACK | MONTEREY ROOM	**3D TRACK | SAN CARLOS ROOM**	**MEMS TRACK | SANTA CLARA**
	Session 1: Fan Out WLP Technologies and Applications	**Session 2 - TSV Processing Considerations**	**Session 3 - MEMS and Sensor Packaging Solutions**
8:30 AM	**Fan-Out Wafer Level Packaging: Market and Technology Trends .....N/A** Thibault Buisson, Yole Développement	**A Study of Microbump Metrology and Defectivity at 20um Pitch and Below for 3D TSV Stacking .....12** Maarten Liebens, IMEC	**Full Hermetic 3D Wafer-Level-Packaging for LED and Sensor Modules.....N/A** Martin Wilke, P.Eng., Fraunhofer IZM
9:00 AM	**Fan-Out WLP Technology as 2D, 3D System in Packaging (SiP) Solution.....N/A** Jong Heon Kim, Nepes Corporation	**TBD**	**Advanced MEMS and Packaging: Photoresist, Adhesive and Thin Film Processing Solutions for Lift-Off Processing .....30** Richard Redburn, EV Group, Steven Sorrentino,
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10:00 AM	**Integration Through Wafer-Level Packaging Approach.....6** Kai Liu, STATS ChipPAC	**Wet Cleaning as an Improved Final Quality Control of DRIE-Produced Features.....24** Travis Acra, Dynaloy	**Scalable High-rate Nanoscale Printing for Electronics, Interconnects, Sensors, Energy and Materials Applications.....N/A** Ahmed Busnaina, Ph.D., Northeastern University
10:30 AM	**Refreshment Break** **Exhibit Hall**		
11:10 AM	**Welcome Comments - Steven Xu, Ph.D., Qualcomm, Conference Chair** **OAK BALLROOM (2ND FLOOR)**		
11:20 AM	**Keynote Address: Rama Alapati, Director of GLOBALFOUNDRIES - Package Architecture & Customer Technology (PACT) High Density Fan-Out: Evolution or Revolution** **OAK BALLROOM (2ND FLOOR)**		
12:15 PM	**Lunch Break** **Exhibit Hall**		
	WLP TRACK | MONTEREY ROOM	**3D TRACK | SAN CARLOS ROOM**	**MEMS TRACK | SANTA CLARA**
	Session 4 - Fan-Out WLCSP	**Session 5 – 3D and TSV Metrology Methodologies**	**Session 6 - MEMS Process Technologies**
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4:00 PM	**Panel Discussion: Fan-Out WLP Panel Processing** **OAK BALLROOM (2nd FLOOR)**		
	Moderator: Jan Vardaman, President, TechSearch International, Inc. Panelists: Jose Campos, NANIUM, S.A. Bill Chen, ASE Tim Olson, Deca Technologies Beth Keser, Ph.D., Qualcomm Thomas Uhrmann, EV Group		
5:30pm - 7:00pm	**Exhibitor Reception** Exhibit Hall		

Sessions at a Glance: Wednesday, October 14

7:00 AM	**Registration Opens** **Bayshore Foyer**		
8:30 AM	**Keynote Address: Sitaram Arkalgud, VP of Invensas - 2.5D/3D IC,Examining Low Cost Alternatives** **OAK BALLROOM (2ND FLOOR)**		
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	WLP TRACK | MONTEREY ROOM	**3D TRACK | SAN CARLOS ROOM**	**WLP TRACK | SANTA CLARA**
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	Moderator: Françoise Von Trapp, 3D InCites **Panelists:** Aric Shorey, Corning, Inc. Thibeault Brisson, Yole Developpement Hughes Metras, CEA-Leti Mike Kelly, Amkor Technology		
3:15 PM	**Refreshment Break** **Exhibit Hall**		
	WLP TRACK | MONTEREY ROOM	**3D TRACK | SAN CARLOS ROOM**	**WLP TRACK | SANTA CLARA**
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